Results from a multi-metallic conductioncooled SRF single-cell cavity

Tesla Technology Collaboration Meeting 4-7 February 2020 CERN

arXiv:2001.10924 [physics.ins-det]

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Tuesday, February 4, 2020

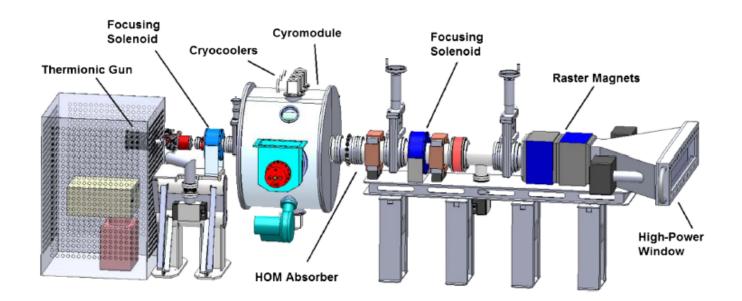




Left to right: K. Harding, J. Henry, D. Tucker, R. Rimmer, G. Ciovati and G. Cheng. Not shown: U. Pudasaini



- Demonstrate operation of a single-cell SRF cavity by conduction cooling using a commercial cryocooler
 - Use Nb₃Sn thin film to achieve lower R_s than Nb at T > 4 K
 - Deposit thick Cu outer shell for good thermal conduction
 - Minimize number of joints between the 4 K stage of cryocooler and the cavity





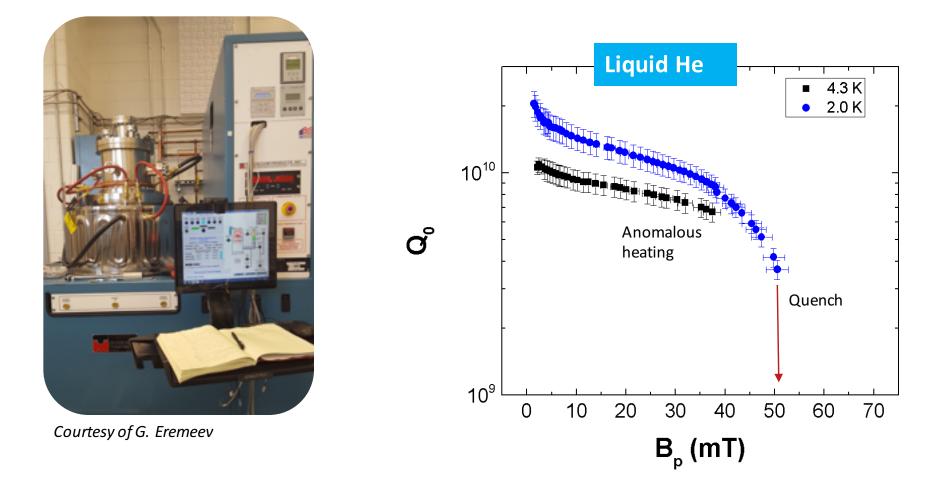
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Nb₃Sn coating

- Nb₃Sn thin film grown by vapor diffusion at 1200 °C on ~2.9 mm thick bulk Nb (large grain) 1.495 GHz single cell cavity
- Synergy with Nb₃Sn development program at JLab



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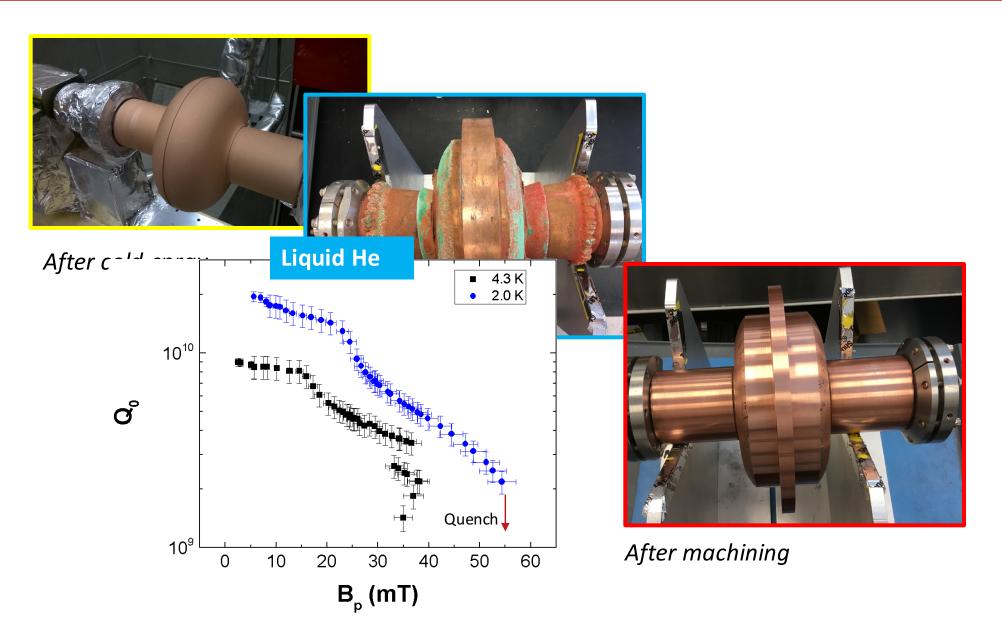


Cu outer coating (1)

- Thermal analysis with ANSYS indicated ≥5 mm thick Cu outer layer to allow reaching ~37 mT with conduction cooling
- Deposit seed layer (~76 μm thick) of Cu on Nb outer surface by cold-spray at CTC, Johnstown, PA
- Deposit ≥5 mm thick oxygen-free Cu on seed layer by electroplating at AJ Tuck Co., Brookfield, CT. A 10" diameter, ½" thick ring was also grown at the equator by electroplating.
- Thermal conductivity measurement on Nb/Cu samples showed ~1000 W/(m K) at 4.3 K



Cu outer coating (2)



Results from a multi-metallic conduction-cooled SRF single-cell cavity



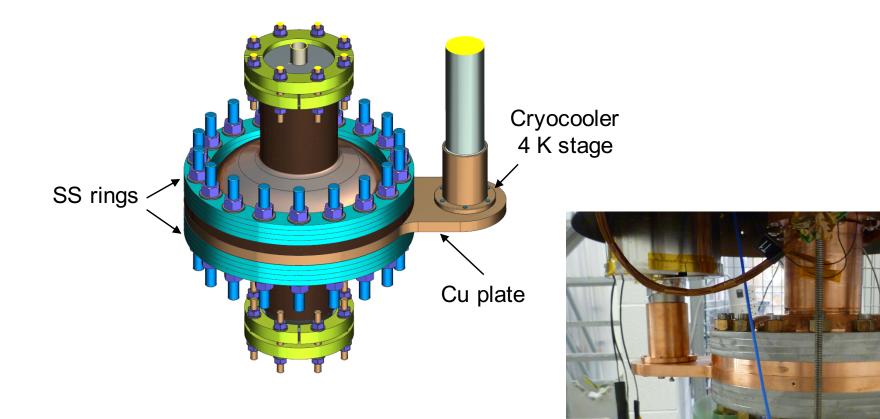
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Cryocooler connection



Cryocooler: Gifford-McMahon type, Sumitomo RDE-418D4, cooling power: 2 W at 4 K

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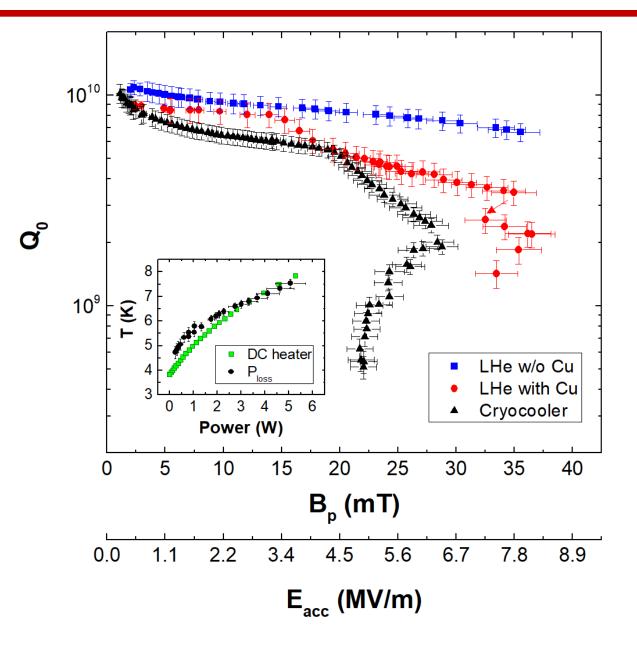
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RF test results

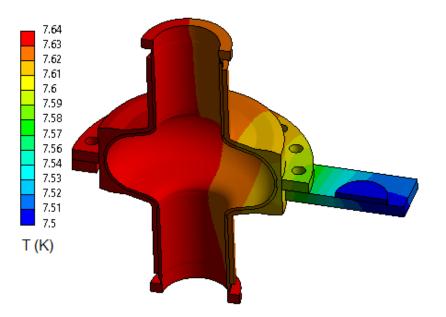
- Cavity temperature after cooldown: ~3.8 K
- T-gradient at 18 K: ~0.09 K/cm
- Max residual B at 18 K: ~14 mG
- Amplitude of microphonics: 13.8 Hz pk-to-pk

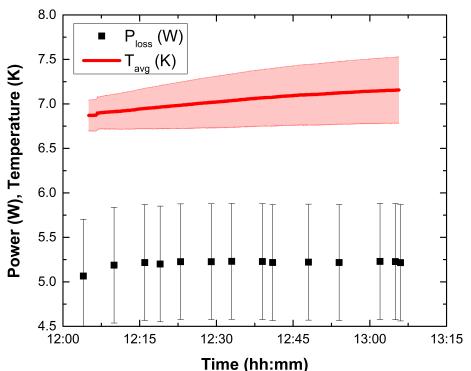


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RF test results

 The cavity was thermally stable during a 1 h operation at P_{diss} = 5 W even with anomalous losses (Q₀ ~ 5e8 at 22 mT)





Cu layer allows remarkable thermal stability



Conclusions

- We developed for the first time a multi-metallic Cu/Nb/Nb₃Sn single-cell cavity
- We were able to demonstrate operation of the cavity up to $B_p \sim 29 \text{ mT} (E_{acc} \sim 6.5 \text{ MV/m})$, limited by defects in the Nb₃Sn film
- The cavity exhibited remarkable thermal stability even with 5 W of power dissipation
- The amplitude of microphonics was well within what has been measured in standard cavities in cryomodules
- These results are a stepping stone towards developing SRF industrial accelerators



Acknowledgments

- B. Golesich at CTC, A. Tuck at AJ Tuck Co.
- JLab cavity production group and machine shop
- E. Daly, G. Eremeev and T. Powers at JLab
- I. Parajuli at ODU
- M. Dale at Sumitomo Cryogenics of America

